## 4-Bit Magnitude Comparator

The MC14585B 4–Bit Magnitude Comparator is constructed with complementary MOS (CMOS) enhancement mode devices. The circuit has eight comparing inputs (A3, B3, A2, B2, A1, B1, A0, B0), three cascading inputs (A < B, A = B, and A > B), and three outputs (A < B, A = B, and A > B). This device compares two 4–bit words (A and B) and determines whether they are "less than", "equal to", or "greater than" by a high level on the appropriate output. For words greater than 4–bits, units can be cascaded by connecting outputs (A > B), (A < B), and (A = B) to the corresponding inputs of the next significant comparator. Inputs (A < B), (A = B), and (A > B) on the least significant (first) comparator are connected to a low, a high, and a low, respectively.

Applications include logic in CPU's, correction and/or detection of instrumentation conditions, comparator in testers, converters, and controls.

- Diode Protection on All Inputs
- Expandable
- Applicable to Binary or 8421-BCD Code
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load over the Rated Temperature Range
- Can be Cascaded See Fig. 3

#### MAXIMUM RATINGS\* (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage	- 0.5 to + 18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage (DC or Transient)	– 0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient), per Pin	± 10	mA
PD	Power Dissipation, per Package†	500	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

<sup>\*</sup> Maximum Ratings are those values beyond which damage to the device may occur. †Temperature Derating:

Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C Ceramic "L" Packages: – 12 mW/°C From 100°C To 125°C

#### **TRUTH TABLE** (x = Don't Care)

Inputs									
	Comp	aring	Cascading			Outputs			
A3, B3	A2, B2	A1, B1	A0, B0	A < B	A = B	A > B	A < B	A = B	A > B
A3 > B3	Х	Х	Х	Х	Х	Х	0	0	1
A3 = B3	A2 > B2	х	х	Х	х	х	0	0	1
A3 = B3	A2 = B2	A1 > B1	х	Х	х	х	0	0	1
A3 = B3	A2 = B2	A1 = B1	A0 > B0	х	х	х	0	0	1
A3 = B3	A2 = B2	A1 = B1	A0 = B0	0	0	Х	0	0	1
A3 = B3	A2 = B2	A1 = B1	A0 = B0	0	1	х	0	1	0
A3 = B3	A2 = B2	A1 = B1	A0 = B0	1	0	х	1	0	0
A3 = B3	A2 = B2	A1 = B1	A0 = B0	1	1	х	1	1	0
A3 = B3	A2 = B2	A1 = B1	A0 < B0	Х	Х	Х	1	0	0
A3 = B3	A2 = B2	A1 < B1	х	Х	х	х	1	0	0
A3 = B3	A2 < B2	х	х	х	х	х	1	0	0
A3 < B3	Х	Х	Х	х	х	х	1	0	0

# MC14585B



L SUFFIX CERAMIC CASE 620



P SUFFIX PLASTIC CASE 648

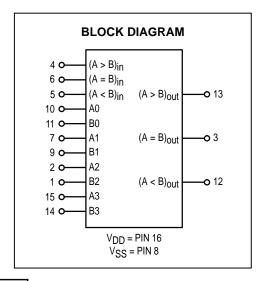


D SUFFIX SOIC CASE 751B

#### ORDERING INFORMATION

MC14XXXBCP Plastic
MC14XXXBCL Ceramic
MC14XXXBD SOIC

 $T_A = -55^{\circ}$  to  $125^{\circ}$ C for all packages.







### **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

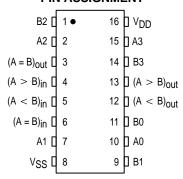
			V <sub>DD</sub>		− 55°C		25°C	25°C		125°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ #	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	VOL	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level	VOH	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level	VIL	5.0 10 15	_ _ _	1.5 3.0 4.0	_ _ _	2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	VIH	5.0 10 15	3.5 7.0 11		3.5 7.0 11	2.75 5.50 8.25		3.5 7.0 11		Vdc
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	Source	ІОН	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	lOL	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l <sub>in</sub>	15	_	±0.1	_	±0.00001	±0.1	_	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		IDD	5.0 10 15	_ _ _	5.0 10 20	_ _ _	0.005 0.010 0.015	5.0 10 20	_ _ _	150 300 600	μAdc
Total Supply Current**†  (Dynamic plus Quiesce Per Package)  (C <sub>L</sub> = 50 pF on all outp buffers switching)		lΤ	5.0 10 15			$I_{T} = (1$	.0.6 μΑ/kHz) f .2 μΑ/kHz) f .8 μΑ/kHz) f	+ I <sub>DD</sub>			μAdc

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I<sub>T</sub> is in  $\mu$ A (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> – V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.001.

#### **PIN ASSIGNMENT**



<sup>\*\*</sup>The formulas given are for the typical characteristics only at 25  $^{\circ}\text{C}.$ 

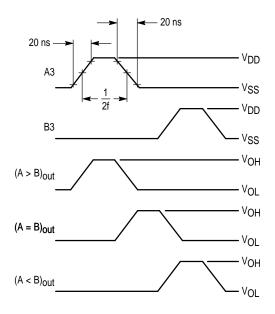
<sup>†</sup>To calculate total supply current at loads other than 50 pF:

#### **SWITCHING CHARACTERISTICS\*** (C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25°C)

Characteristic	Symbol	V <sub>DD</sub>	Min	Тур#	Max	Unit
Output Rise and Fall Time  t <sub>TLH</sub> , t <sub>THL</sub> = (1.5 ns/pF) C <sub>L</sub> + 25 ns  t <sub>TLH</sub> , t <sub>THL</sub> = (0.75 ns/pF) C <sub>L</sub> + 12.5 ns  t <sub>TLH</sub> , t <sub>THL</sub> = (0.55 ns/pF) C <sub>L</sub> + 9.5 ns	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15		100 50 40	200 100 80	ns
Turn-On, Turn-Off Delay Time  tplH, tpHL = (1.7 ns/pF) C <sub>L</sub> + 345 ns  tplH, tpHL = (0.66 ns/pF) C <sub>L</sub> + 147 ns  tplH, tpHL = (0.5 ns/pF) C <sub>L</sub> + 105 ns	tpLH, tpHL	5.0 10 15		430 180 130	860 360 260	ns

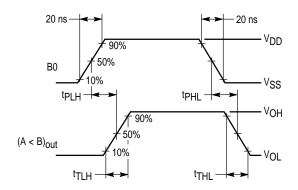
<sup>\*</sup>The formulas given are for the typical characteristics only at 25°C.

<sup>#</sup>Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



Inputs (A>B) and (A=B) high, and inputs B2, A2, B1, A1, B0, A0 and (A<B) low. f in respect to a system clock.

Figure 1. Dynamic Power Dissipation Signal Waveforms



Inputs (A>B) and (A=B) high, and inputs B3, A3, B2, A2, B1, A1, A0, and (A<B) low.

Figure 2. Dynamic Signal Waveforms

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \le (V_{in} \text{ or } V_{out}) \le V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either VSS or VDD). Unused outputs must be left open.

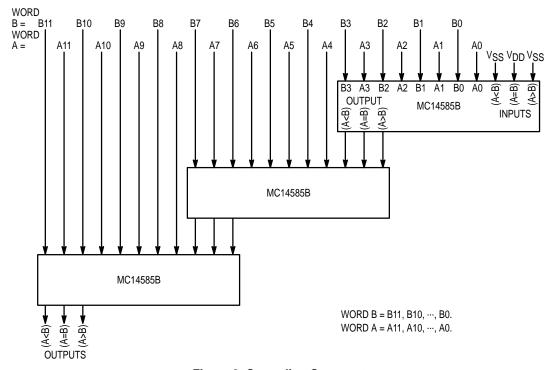
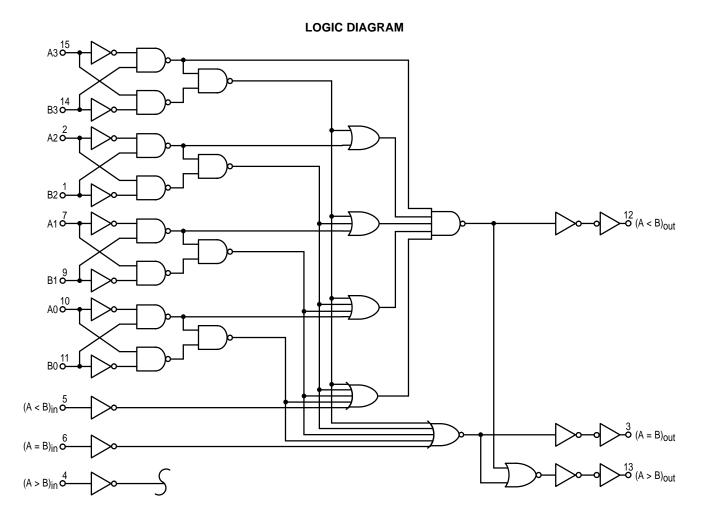
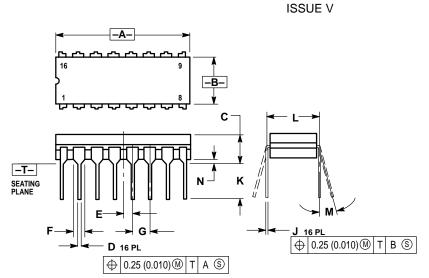


Figure 3. Cascading Comparators



#### **OUTLINE DIMENSIONS**

### **L SUFFIX** CERAMIC DIP PACKAGE CASE 620-10



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

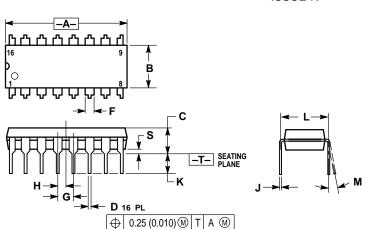
  3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

  4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC RODY.

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.750	0.785	19.05	19.93		
В	0.240	0.295	6.10	7.49		
C		0.200		5.08		
D	0.015	0.020	0.39	0.50		
Е	0.050	BSC	1.27 BSC			
F	0.055	0.065	1.40	1.65		
G	0.100	BSC	2.54 BSC			
Н	0.008	0.015	0.21	0.38		
K	0.125	0.170	3.18	4.31		
L	0.300 BSC		7.62	BSC		
M	0 °	15°	0 °	15°		
N	0.020	0.040	0.51	1.01		

#### **P SUFFIX**

PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

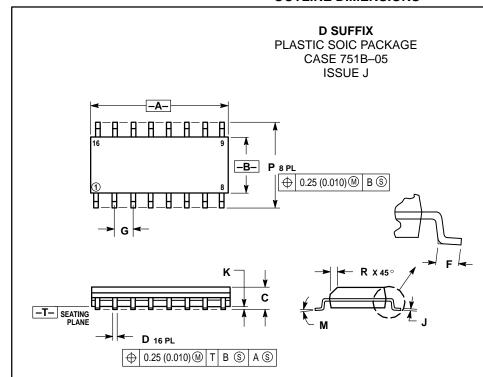
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

#### **OUTLINE DIMENSIONS**



- DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	METERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
U	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
М	0°	7°	0°	7°	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

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